

Fair-Rite P/N 2506031217Z0

Z Chip Bead Material Grade

Nominal Chemical Composition

Supporting notes:

1. P/N 2506031217Z0 consists of:
 - a core Z Chip Bead Material Grade
 - b Termination Plating SnNiAg
2. Moisture Sensitivity Level (MSL)= 1
3. Max Reflow Temp= 260 degC
4. Max Time at Max Reflow Temp= 40 sec
5. RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
6. RoHS Conversion Date= 1/1/2005
7. RoHS Compliance Marking is Contained on Shipping Labels

| <u>Ferrite -Compound</u> | <u>CAS Number</u> | <u>wt %</u> | Wt of core (g)= | |
|--------------------------|-------------------|-------------|-----------------|---|
| | | | 0.0048 | |
| Fe2O3 | 1309-37-1 | 64 | 0.00307 | Compound Weight (g) Breakdown of Z Chip Bead Material Grade |
| ZnO | 1314-13-2 | 15 | 0.00072 | |
| NiO | 1313-99-1 | 13 | 0.00062 | |
| CuO | 1317-38-0 | 5 | 0.00024 | |
| CoO | 1307-96-6 | 2 | 0.00010 | |
| MnO | 1344-43-0 | 1 | 0.00005 | |

| <u>Termination Plating - Elements</u> | <u>CAS Number</u> | <u>wt %</u> | Wt of termination (g)= | |
|---|-------------------|-------------|------------------------|--|
| | | | 0.0012 | |
| Sn | 7440-31-5 | 14.3 | 0.00017 | Element Weight (g) Breakdown of Pb- Free Termination Plating |
| Ni | 7440-02-0 | 6.9 | 0.00008 | |
| Ag | 7440-22-4 | 78.8 | 0.00095 | |

Calculated Maximum Levels of RoHS Restricted Substances Present in Z Chip Bead Material Grade

| <u>Impurity Substance</u> | <u>RoHS Threshold (ppm):</u> | <u>ppm</u> | Wt of core (g)= | |
|-------------------------------|----------------------------------|------------|-----------------|---|
| | | | 0.005 | |
| Cr+6 | 1000 | 0.00 | 0 | RoHS Impurity Substance Weight (g) Breakdown of Z Chip Bead Material Grade |
| Cd | 100 | 0.00 | 0 | |
| Hg | 1000 | 0.00 | 0 | |
| Pb | 1000 | 0.00 | 0 | |
| PBB | 1000 | 0.00 | 0 | |
| PBDE | 1000 | 0.00 | 0 | |